

# SN54HC32, SN74HC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCLS200B – DECEMBER 1982 – REVISED MAY 1997

- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

## description

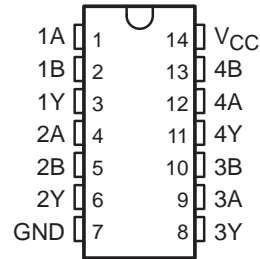
These devices contain four independent 2-input OR gates. They perform the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = A + B$  in positive logic.

The SN54HC32 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74HC32 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

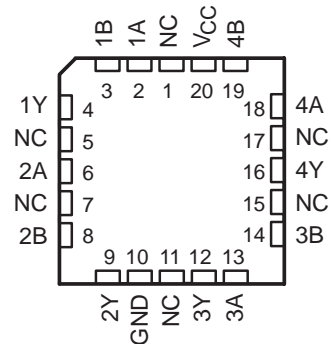
FUNCTION TABLE  
(each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

SN54HC32 . . . J OR W PACKAGE  
SN74HC32 . . . D, DB, N, OR PW PACKAGE  
(TOP VIEW)

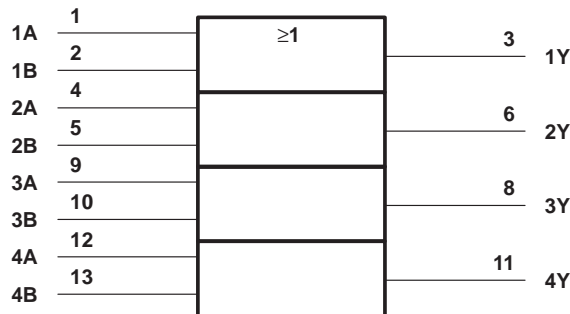


SN54HC32 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, N, PW, and W packages.

## logic diagram (positive logic)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1997, Texas Instruments Incorporated

# SN54HC32, SN74HC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCLS200B – DECEMBER 1982 – REVISED MAY 1997

## absolute maximum ratings over operating free-air temperature range†

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through $V_{CC}$ or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
D package	127°C/W
DB package	158°C/W
N package	78°C/W
PW package	170°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

## recommended operating conditions

		SN54HC32			SN74HC32			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5		1.5		V	
		$V_{CC} = 4.5\text{ V}$	3.15		3.15			
		$V_{CC} = 6\text{ V}$	4.2		4.2			
$V_{IL}$	Low-level input voltage	$V_{CC} = 2\text{ V}$	0	0.5	0	0.5	V	
		$V_{CC} = 4.5\text{ V}$	0	1.35	0	1.35		
		$V_{CC} = 6\text{ V}$	0	1.8	0	1.8		
$V_I$	Input voltage	0	$V_{CC}$		0	$V_{CC}$		V
$V_O$	Output voltage	0	$V_{CC}$		0	$V_{CC}$		V
$t_t$	Input transition (rise and fall) time	$V_{CC} = 2\text{ V}$	0	1000	0	1000	ns	
		$V_{CC} = 4.5\text{ V}$	0	500	0	500		
		$V_{CC} = 6\text{ V}$	0	400	0	400		
$T_A$	Operating free-air temperature	-55	125	-40	85	°C		



# SN54HC32, SN74HC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCLS200B – DECEMBER 1982 – REVISED MAY 1997

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC32		SN74HC32		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100		±1000		±1000	nA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V					40		20	μA
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF

**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC32		SN74HC32		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	2 V		50	100		150		125	ns
			4.5 V		10	20		30		25	
			6 V		8	17		25		21	
t <sub>t</sub>		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

**operating characteristics, T<sub>A</sub> = 25°C**

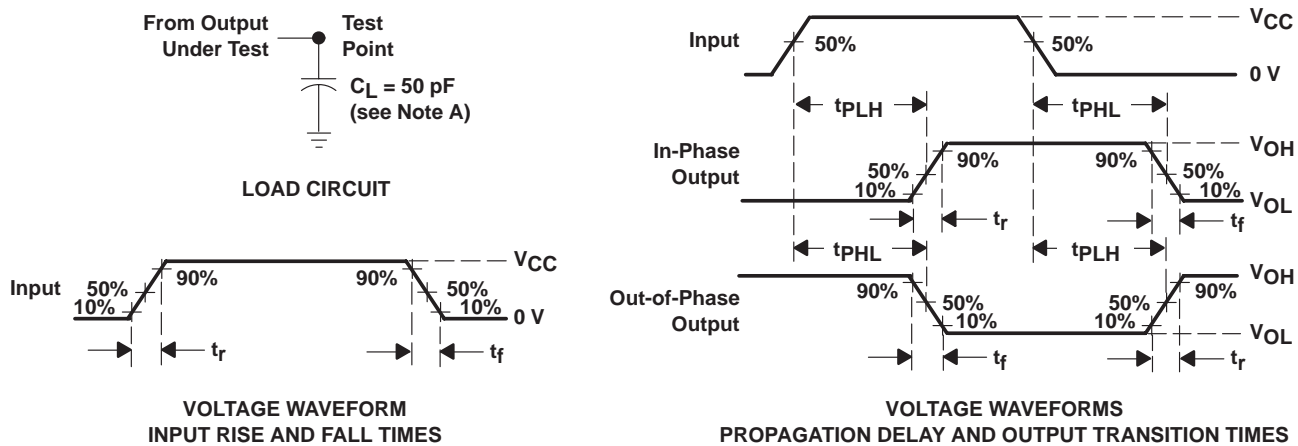
PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance per gate	No load	20	pF



# SN54HC32, SN74HC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCLS200B – DECEMBER 1982 – REVISED MAY 1997

## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## **IMPORTANT NOTICE**

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

**CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.**

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.